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Sheet 1 of 1

Form PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	ATTY. DKT. NO. 219.40232X00	SERIAL NO. 10/077,967
	APPLICANT Sarah E. KIM et al.	
	FILING DATE February 20, 2002	GROUP 2822

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
	AA					
	AB					
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FOREIGN PATENT DOCUMENTS

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						Yes	No
	AM						
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	AO						
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	AS						
	AT						

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

MT	AU	"Ultra Thin Electronics for Space Applications", 2001 Electronic Components and Technology Conference, 2001 IEEE, 5 pages.
J	AV	"Copper Wafer Bonding"; A. Fan, A. Rahman, and R. Reif; Electrochemical and Solid-State Letters, 2 (10) 534-536 (1999)
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Examiner Michael Trinkl		Date Considered 9/5/03